



Click [here](#) for the 3D model.

### Dimensions

Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	0.78mm +/-0.10mm
B	0.5mm +/-0.25mm

### Packaging Specifications

Packaging	Bulk, Bag
Packaging Quantity	1

### General Information

Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

### Specifications

Capacitance	4700 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	20%
Voltage DC	250 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms